IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mf	g Informati	ion		
upplier Infor															
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
onsemi												2023-06-08			
Contact Name		7	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards	I	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*	7	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stev	wards	I	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reques	Requester Item Number Mfn		Mfr Item Number Mfr Item Name				Effective Date	e Versi	on	Manufacturing Site	V	Veight*	UOM	Unit Type	
		NCV5661MNADJT2G 1 A LDO LINEAR REC		REG		2023-06-08			MY1		3.36	mg	Each		
Ianufacturin	g Proccess Informatio	on													
Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Temperatur		re Max Time at Peak	Temperatu	are Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 1			260 C		30	second	ds 3					
omments															
vel 1 - maximum	time at peak temperature	e during solde	ering is 10-30	seconds											
or more informa	tion regarding material co	omposition pl	ease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.99	mg	Supplier	Silicon (Si)	7440-21-3		0.99	mg
Die Attach	0.24	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.0768	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.1632	mg
Die Attach Epoxy	0.0	mg		Epoxy resin	proprietary data		0	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0	mg
Lead Frame	5.9	mg	Supplier	Silver (Ag)	7440-22-4		0.118	mg
			Supplier	Iron (Fe)	7439-89-6		0.1298	mg
			Supplier	Copper (Cu)	7440-50-8		5.6522	mg
Mold Compound-Black	14.8	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		1.184	mg
			Supplier	Carbon Black (C)	1333-86-4		0.074	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.296	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.802	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.444	mg
Plating	1.22	mg	Supplier	Tin (Sn)	7440-31-5		1.22	mg
Wire Bond - Au	0.21	mg	Supplier	Gold (Au)	7440-57-5		0.21	mg